

ABSTRACT OF THE DISCLOSURE

When etching is performed with respect to a silicon-containing material by using a dry etching apparatus having a dual power source, the application of bias power is initiated
5 before oxidization proceeds at a surface of the silicon-containing material. Specifically, the application of the bias power is initiated before the application of source power is initiated. Alternatively, the source power and the bias power are applied such that the effective value of the
10 source power reaches a second predetermined value after the effective value of the bias power reaches a first predetermined value.